



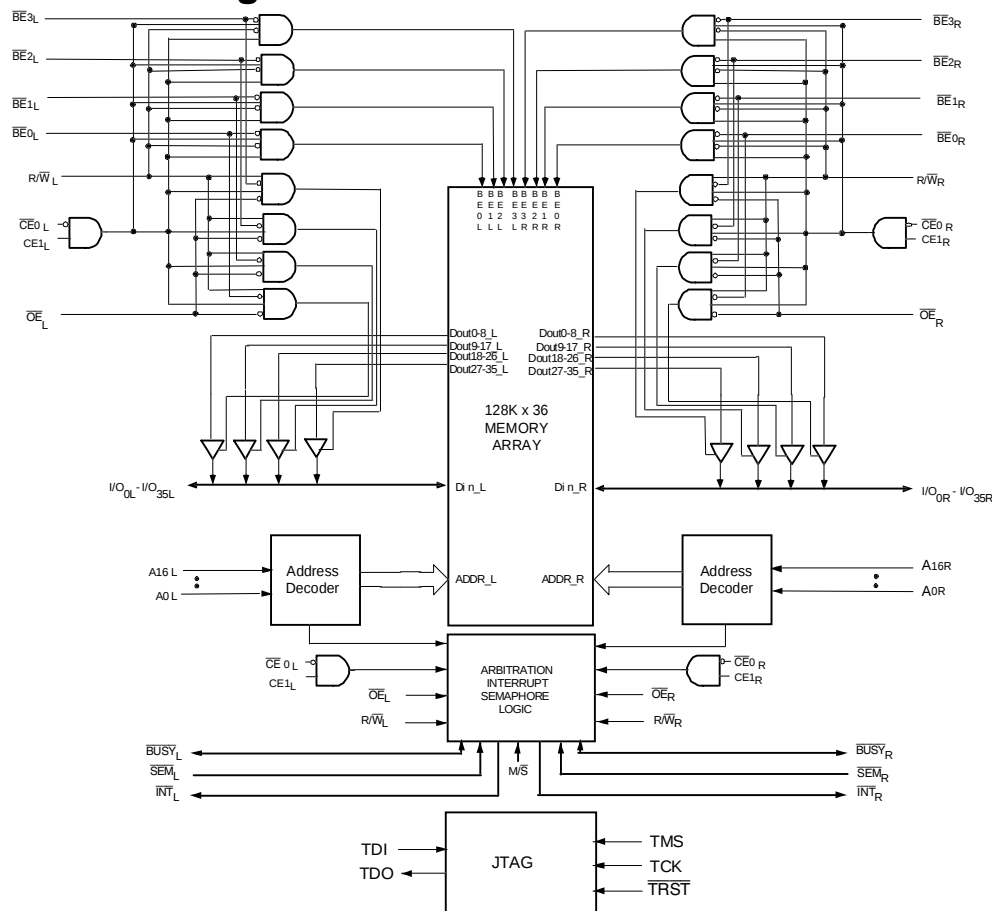
HIGH-SPEED 3.3V 128K x 36 ASYNCHRONOUS DUAL-PORT STATIC RAM

PRELIMINARY
IDT70V659S

Features

- ♦ True Dual-Port memory cells which allow simultaneous access of the same memory location
- ♦ High-speed access
 - Commercial: 10/12/15ns (max.)
 - Industrial: 12/15ns (max.)
- ♦ Dual chip enables allow for depth expansion without external logic
- ♦ IDT70V659 easily expands data bus width to 72 bits or more using the Master/Slave select when cascading more than one device
- ♦ $M/\bar{S} = V_{IH}$ for $\overline{BUSY}$ output flag on Master, $M/\bar{S} = V_{IL}$ for $\overline{BUSY}$ input on Slave
- ♦ Busy and Interrupt Flags
- ♦ On-chip port arbitration logic
- ♦ Full on-chip hardware support of semaphore signaling between ports
- ♦ Fully asynchronous operation from either port
- ♦ Separate byte controls for multiplexed bus and bus matching compatibility
- ♦ Supports JTAG features compliant to IEEE 1149.1
- ♦ LVTTTL-compatible, single 3.3V ($\pm 150mV$) power supply for core
- ♦ LVTTTL-compatible, selectable 3.3V ($\pm 150mV$)/2.5V ($\pm 100mV$) power supply for I/Os and control signals on each port
- ♦ Available in a 208-pin Plastic Quad Flatpack, 208-ball fine pitch Ball Grid Array, and 256-ball Ball Grid Array
- ♦ Industrial temperature range ($-40^{\circ}C$ to $+85^{\circ}C$) is available for selected speeds

Functional Block Diagram



NOTES:

1. $\overline{BUSY}$ is an input as a Slave ($M/\bar{S}=V_{IL}$) and an output when it is a Master ($M/\bar{S}=V_{IH}$).
2. $\overline{BUSY}$ and $\overline{INT}$ are non-tri-state totem-pole outputs (push-pull).

4869 drw 01

JUNE 2001

Description

The IDT70V659 is a high-speed 128K x 36 Asynchronous Dual-Port Static RAM. The IDT70V659 is designed to be used as a stand-alone 4608K-bit Dual-Port RAM or as a combination MASTER/SLAVE Dual-Port RAM for 72-bit-or-more word system. Using the IDT MASTER/SLAVE Dual-Port RAM approach in 72-bit or wider memory system applications results in full-speed, error-free operation without the need for additional discrete logic.

This device provides two independent ports with separate control,

address, and I/O pins that permit independent, asynchronous access for reads or writes to any location in memory. An automatic power down feature controlled by the chip enables (either $\overline{CE}_0$ or CE_1) permit the on-chip circuitry of each port to enter a very low standby power mode.

The 70V659 can support an operating voltage of either 3.3V or 2.5V on one or both ports, controlled by the OPT pins. The power supply for the core of the device (V_{DD}) remains at 3.3V.

Pin Configurations^(1,2,3,4)

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17		
A	I/O19L	I/O18L	VSS	TDO	NC	A16L	A12L	A8L	$\overline{BE}_{1L}$	VDD	$\overline{SEM}_L$	$\overline{INT}_L$	A4L	A0L	OPTL	I/O17L	VSS	A	
B	I/O20R	VSS	I/O18R	TDI	NC	A13L	A9L	$\overline{BE}_{2L}$	$\overline{CE}_{0L}$	VSS	$\overline{BUS}_L$	A5L	A1L	VSS	VDDQR	I/O16L	I/O15R	B	
C	VDDQL	I/O19R	VDDQR	VDD	NC	A14L	A10L	$\overline{BE}_{3L}$	CE1L	VSS	R/ $\overline{WL}$	A6L	A2L	VDD	I/O16R	I/O15L	VSS	C	
D	I/O22L	VSS	I/O21L	I/O20L	A15L	A11L	A7L	$\overline{BE}_{0L}$	VDD	$\overline{OE}_L$	NC	A3L	VDD	I/O17R	VDDQL	I/O14L	I/O14R	D	
E	I/O23L	I/O22R	VDDQR	I/O21R	70V659BF BF-208 ⁽⁵⁾ 208-Ball BGA Top View ⁽⁶⁾										I/O12L	I/O13R	VSS	I/O13L	E
F	VDDQL	I/O23R	I/O24L	VSS											VSS	I/O12R	I/O11L	VDDQR	F
G	I/O26L	VSS	I/O25L	I/O24R											I/O9L	VDDQL	I/O10L	I/O11R	G
H	VDD	I/O26R	VDDQR	I/O25R											VDD	I/O9R	VSS	I/O10R	H
J	VDDQL	VDD	VSS	VSS											VSS	VDD	VSS	VDDQR	J
K	I/O28R	VSS	I/O27R	VSS											I/O7R	VDDQL	I/O8R	VSS	K
L	I/O29R	I/O28L	VDDQR	I/O27L											I/O6R	I/O7L	VSS	I/O8L	L
M	VDDQL	I/O29L	I/O30R	VSS											VSS	I/O6L	I/O5R	VDDQR	M
N	I/O31L	VSS	I/O31R	I/O30L											I/O3R	VDDQL	I/O4R	I/O5L	N
P	I/O32R	I/O32L	VDDQR	I/O35R	$\overline{TRST}$	A16R	A12R	A8R	$\overline{BE}_{1R}$	VDD	$\overline{SEM}_R$	$\overline{INT}_R$	A4R	I/O2L	I/O3L	VSS	I/O4L	P	
R	VSS	I/O33L	I/O34R	TCK	NC	A13R	A9R	$\overline{BE}_{2R}$	$\overline{CE}_{1R}$	VSS	$\overline{BUS}_R$	A5R	A1R	VSS	VDDQL	I/O1R	VDDQR	R	
T	I/O33R	I/O34L	VDDQL	TMS	NC	A14R	A10R	$\overline{BE}_{3R}$	CE1R	VSS	R/ $\overline{WL}$	A6R	A2R	VSS	I/O0R	VSS	I/O2R	T	
U	VSS	I/O35L	VDD	NC	A15R	A11R	A7R	$\overline{BE}_{0R}$	VDD	$\overline{OE}_R$	M/ $\overline{S}$	A3R	A0R	VDD	OPTR	I/O0L	I/O1L	U	

4869 tbl 02b

NOTES:

1. All V_{DD} pins must be connected to 3.3V power supply.
2. All V_{DDQ} pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to V_{IH} (3.3V) and 2.5V if OPT pin for that port is set to V_{IL} (0V).
3. All V_{SS} pins must be connected to ground.
4. Package body is approximately 15mm x 15mm x 1.4mm with 0.8mm ball pitch.
5. This package code is used to reference the package diagram.
6. This text does not indicate orientation of the actual part-marking.

Pin Configurations^(1,2,3,4) (con't.)



NOTES:

1. All VDD pins must be connected to 3.3V power supply.
2. All VDDQ pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to VIH (3.3V) and 2.5V if OPT pin for that port is set to VIL (0V).
3. All VSS pins must be connected to ground.
4. Package body is approximately 28mm x 28mm x 3.5mm.
5. This package code is used to reference the package diagram.
6. This text does not indicate orientation of the actual part-marking.

Pin Configuration^(1,2,3,4) (con't.)

70V659BC
BC-256⁽⁵⁾

256-Pin BGA
Top View⁽⁶⁾

A1 NC	A2 TDI	A3 NC	A4 NC	A5 A14L	A6 A11L	A7 A8L	A8 BE ₂ L	A9 CE ₁ L	A10 OE _L	A11 INT _L	A12 A5L	A13 A2L	A14 A0L	A15 NC	A16 NC
B1 I/O ₁₈ L	B2 NC	B3 TDO	B4 NC	B5 A15L	B6 A12L	B7 A9L	B8 BE ₃ L	B9 CE ₀ L	B10 R/W _L	B11 NC	B12 A4L	B13 A1L	B14 NC	B15 I/O ₁₇ L	B16 NC
C1 I/O ₁₈ R	C2 I/O ₁₉ L	C3 V _{SS}	C4 A16L	C5 A13L	C6 A10L	C7 A7L	C8 BE ₁ L	C9 BE ₀ L	C10 SEM _L	C11 BUSY _L	C12 A6L	C13 A3L	C14 OPT _L	C15 I/O ₁₇ R	C16 I/O ₁₆ L
D1 I/O ₂₀ R	D2 I/O ₁₉ R	D3 I/O ₂₀ L	D4 V _{DD}	D5 V _{DD} QL	D6 V _{DD} QL	D7 V _{DD} QR	D8 V _{DD} QR	D9 V _{DD} QL	D10 V _{DD} QL	D11 V _{DD} QR	D12 V _{DD} QR	D13 V _{DD}	D14 I/O ₁₅ R	D15 I/O ₁₅ L	D16 I/O ₁₆ R
E1 I/O ₂₁ R	E2 I/O ₂₁ L	E3 I/O ₂₂ L	E4 V _{DD} QL	E5 V _{DD}	E6 V _{DD}	E7 V _{SS}	E8 V _{SS}	E9 V _{SS}	E10 V _{SS}	E11 V _{DD}	E12 V _{DD}	E13 V _{DD} QR	E14 I/O ₁₃ L	E15 I/O ₁₄ L	E16 I/O ₁₄ R
F1 I/O ₂₃ L	F2 I/O ₂₂ R	F3 I/O ₂₃ R	F4 V _{DD} QL	F5 V _{DD}	F6 V _{SS}	F7 V _{SS}	F8 V _{SS}	F9 V _{SS}	F10 V _{SS}	F11 V _{SS}	F12 V _{DD}	F13 V _{DD} QR	F14 I/O ₁₂ R	F15 I/O ₁₃ R	F16 I/O ₁₂ L
G1 I/O ₂₄ R	G2 I/O ₂₄ L	G3 I/O ₂₅ L	G4 V _{DD} QR	G5 V _{SS}	G6 V _{SS}	G7 V _{SS}	G8 V _{SS}	G9 V _{SS}	G10 V _{SS}	G11 V _{SS}	G12 V _{SS}	G13 V _{DD} QL	G14 I/O ₁₀ L	G15 I/O ₁₁ L	G16 I/O ₁₁ R
H1 I/O ₂₆ L	H2 I/O ₂₅ R	H3 I/O ₂₆ R	H4 V _{DD} QR	H5 V _{SS}	H6 V _{SS}	H7 V _{SS}	H8 V _{SS}	H9 V _{SS}	H10 V _{SS}	H11 V _{SS}	H12 V _{SS}	H13 V _{DD} QL	H14 I/O ₉ R	H15 I/O ₉ L	H16 I/O ₁₀ R
J1 I/O ₂₇ L	J2 I/O ₂₈ R	J3 I/O ₂₇ R	J4 V _{DD} QL	J5 V _{SS}	J6 V _{SS}	J7 V _{SS}	J8 V _{SS}	J9 V _{SS}	J10 V _{SS}	J11 V _{SS}	J12 V _{SS}	J13 V _{DD} QR	J14 I/O ₈ R	J15 I/O ₇ R	J16 I/O ₈ L
K1 I/O ₂₉ R	K2 I/O ₂₉ L	K3 I/O ₂₈ L	K4 V _{DD} QL	K5 V _{SS}	K6 V _{SS}	K7 V _{SS}	K8 V _{SS}	K9 V _{SS}	K10 V _{SS}	K11 V _{SS}	K12 V _{SS}	K13 V _{DD} QR	K14 I/O ₆ R	K15 I/O ₆ L	K16 I/O ₇ L
L1 I/O ₃₀ L	L2 I/O ₃₁ R	L3 I/O ₃₀ R	L4 V _{DD} QR	L5 V _{DD}	L6 V _{SS}	L7 V _{SS}	L8 V _{SS}	L9 V _{SS}	L10 V _{SS}	L11 V _{SS}	L12 V _{DD}	L13 V _{DD} QL	L14 I/O ₅ L	L15 I/O ₄ R	L16 I/O ₅ R
M1 I/O ₃₂ R	M2 I/O ₃₂ L	M3 I/O ₃₁ L	M4 V _{DD} QR	M5 V _{DD}	M6 V _{DD}	M7 V _{SS}	M8 V _{SS}	M9 V _{SS}	M10 V _{SS}	M11 V _{DD}	M12 V _{DD}	M13 V _{DD} QL	M14 I/O ₃ R	M15 I/O ₃ L	M16 I/O ₄ L
N1 I/O ₃₃ L	N2 I/O ₃₄ R	N3 I/O ₃₃ R	N4 V _{DD}	N5 V _{DD} QR	N6 V _{DD} QR	N7 V _{DD} QL	N8 V _{DD} QL	N9 V _{DD} QR	N10 V _{DD} QR	N11 V _{DD} QL	N12 V _{DD} QL	N13 V _{DD}	N14 I/O ₂ L	N15 I/O ₁ R	N16 I/O ₂ R
P1 I/O ₃₅ R	P2 I/O ₃₄ L	P3 TMS	P4 A16R	P5 A13R	P6 A10R	P7 A7R	P8 BE ₁ R	P9 BE ₀ R	P10 SEM _R	P11 BUSY _R	P12 A6R	P13 A3R	P14 I/O ₀ L	P15 I/O ₀ R	P16 I/O ₁ L
R1 I/O ₃₅ L	R2 NC	R3 TRST	R4 NC	R5 A15R	R6 A12R	R7 A9R	R8 BE ₃ R	R9 CE ₀ R	R10 R/W _R	R11 M/S	R12 A4R	R13 A1R	R14 OPT _R	R15 NC	R16 NC
T1 NC	T2 TCK	T3 NC	T4 NC	T5 A14R	T6 A11R	T7 A8R	T8 BE ₂ R	T9 CE ₁ R	T10 OE _R	T11 INT _R	T12 A5R	T13 A2R	T14 A0R	T15 NC	T16 NC

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NOTES:

1. All V_{DD} pins must be connected to 3.3V power supply.
2. All V_{DDQ} pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to V_{IH} (3.3V), and 2.5V if OPT pin for that port is set to V_{IL} (0V).
3. All V_{SS} pins must be connected to ground supply.
4. Package body is approximately 17mm x 17mm x 1.4mm, with 1.0mm ball-pitch.
5. This package code is used to reference the package diagram.
6. This text does not indicate orientation of the actual part-marking.

Pin Names

Left Port	Right Port	Names
$\overline{CE}_{0L}$, CE_{1L}	$\overline{CE}_{0R}$, CE_{1R}	Chip Enables
$R/\overline{WL}$	$R/\overline{WR}$	Read/Write Enable
$\overline{OE}_L$	$\overline{OE}_R$	Output Enable
A_{0L} - A_{16L}	A_{0R} - A_{16R}	Address
I/O_{0L} - I/O_{35L}	I/O_{0R} - I/O_{35R}	Data Input/Output
$\overline{SEM}_L$	$\overline{SEM}_R$	Semaphore Enable
INT_L	INT_R	Interrupt Flag
$BUSY_L$	$BUSY_R$	Busy Flag
$\overline{BE}_{0L}$ - $\overline{BE}_{3L}$	$\overline{BE}_{0R}$ - $\overline{BE}_{3R}$	Byte Enables (9-bit bytes)
V_{DDQL}	V_{DDQR}	Power (I/O Bus) (3.3V or 2.5V) ⁽¹⁾
OPT_L	OPT_R	Option for selecting V_{DDQX} ^(1,2)
$M/\overline{S}$		Master or Slave Select
V_{DD}		Power (3.3V) ⁽¹⁾
V_{SS}		Ground (0V)
TDI		Test Data Input
TDO		Test Data Output
TCK		Test Logic Clock (10MHz)
TMS		Test Mode Select
$\overline{TRST}$		Reset (Initialize TAP Controller)

4869 tbl 01

NOTES:

1. V_{DD} , OPT_X , and V_{DDQX} must be set to appropriate operating levels prior to applying inputs on I/O_X .
2. OPT_X selects the operating voltage levels for the I/O s and controls on that port. If OPT_X is set to V_{IH} (3.3V), then that port's I/O s and controls will operate at 3.3V levels and V_{DDQX} must be supplied at 3.3V. If OPT_X is set to V_{IL} (0V), then that port's I/O s and controls will operate at 2.5V levels and V_{DDQX} must be supplied at 2.5V. The OPT pins are independent of one another—both ports can operate at 3.3V levels, both can operate at 2.5V levels, or either can operate at 3.3V with the other at 2.5V.

Truth Table I—Read/Write and Enable Control^(1,2)

$\overline{OE}$	$\overline{SEM}$	$\overline{CE_0}$	CE_1	$\overline{BE_3}$	$\overline{BE_2}$	$\overline{BE_1}$	$\overline{BE_0}$	$R/\overline{W}$	Byte 3 I/O ₂₇₋₃₅	Byte 2 I/O ₁₈₋₂₆	Byte 1 I/O ₉₋₁₇	Byte 0 I/O ₀₋₈	MODE
X	H	H	X	X	X	X	X	X	High-Z	High-Z	High-Z	High-Z	Deselected—Power Down
X	H	X	L	X	X	X	X	X	High-Z	High-Z	High-Z	High-Z	Deselected—Power Down
X	H	L	H	H	H	H	H	X	High-Z	High-Z	High-Z	High-Z	All Bytes Deselected
X	H	L	H	H	H	H	L	L	High-Z	High-Z	High-Z	D _{IN}	Write to Byte 0 Only
X	H	L	H	H	H	L	H	L	High-Z	High-Z	D _{IN}	High-Z	Write to Byte 1 Only
X	H	L	H	H	L	H	H	L	High-Z	D _{IN}	High-Z	High-Z	Write to Byte 2 Only
X	H	L	H	L	H	H	H	L	D _{IN}	High-Z	High-Z	High-Z	Write to Byte 3 Only
X	H	L	H	H	H	L	L	L	High-Z	High-Z	D _{IN}	D _{IN}	Write to Lower 2 Bytes Only
X	H	L	H	L	L	H	H	L	D _{IN}	D _{IN}	High-Z	High-Z	Write to Upper 2 bytes Only
X	H	L	H	L	L	L	L	L	D _{IN}	D _{IN}	D _{IN}	D _{IN}	Write to All Bytes
L	H	L	H	H	H	H	L	H	High-Z	High-Z	High-Z	D _{OUT}	Read Byte 0 Only
L	H	L	H	H	H	L	H	H	High-Z	High-Z	D _{OUT}	High-Z	Read Byte 1 Only
L	H	L	H	H	L	H	H	H	High-Z	D _{OUT}	High-Z	High-Z	Read Byte 2 Only
L	H	L	H	L	H	H	H	H	D _{OUT}	High-Z	High-Z	High-Z	Read Byte 3 Only
L	H	L	H	H	H	L	L	H	High-Z	High-Z	D _{OUT}	D _{OUT}	Read Lower 2 Bytes Only
L	H	L	H	L	L	H	H	H	D _{OUT}	D _{OUT}	High-Z	High-Z	Read Upper 2 Bytes Only
L	H	L	H	L	L	L	L	H	D _{OUT}	D _{OUT}	D _{OUT}	D _{OUT}	Read All Bytes
H	H	L	H	L	L	L	L	X	High-Z	High-Z	High-Z	High-Z	Outputs Disabled

NOTES:

- "H" = V_{IH}, "L" = V_{IL}, "X" = Don't Care.
- It is possible to read or write any combination of bytes during a given access. A few representative samples have been illustrated here.

4869 tbl 02

Truth Table II – Semaphore Read/Write Control⁽¹⁾

Inputs ⁽¹⁾								Outputs		Mode
$\overline{CE}^{(2)}$	$R/\overline{W}$	$\overline{OE}$	$\overline{BE_3}$	$\overline{BE_2}$	$\overline{BE_1}$	$\overline{BE_0}$	$\overline{SEM}$	I/O ₁₋₃₅	I/O ₀	
H	H	L	L	L	L	L	L	DATA _{OUT}	DATA _{OUT}	Read Data in Semaphore Flag ⁽³⁾
H	↑	X	X	X	X	L	L	X	DATA _{IN}	Write I/O ₀ into Semaphore Flag
L	X	X	X	X	X	X	L	—	—	Not Allowed

NOTES:

- There are eight semaphore flags written to I/O₀ and read from all the I/Os (I/O₀-I/O₃₅). These eight semaphore flags are addressed by A₀-A₂.
- $\overline{CE} = L$ occurs when $\overline{CE_0} = V_{IL}$ and $CE_1 = V_{IH}$.
- Each byte is controlled by the respective $\overline{BE}_n$. To read data $\overline{BE}_n = V_{IL}$.

486 tbl 03

Maximum Operating Temperature and Supply Voltage⁽¹⁾

Grade	Ambient Temperature	GND	V _{DD}
Commercial	0°C to +70°C	0V	3.3V $\pm$ 150mV
Industrial	-40°C to +85°C	0V	3.3V $\pm$ 150mV

4869 tbl 04

NOTES:

1. This is the parameter TA. This is the "instant on" case temperature.

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial	Unit
V _{TERM} ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
T _{BIAS}	Temperature Under Bias	-55 to +125	°C
T _{STG}	Storage Temperature	-65 to +150	°C
I _{OUT}	DC Output Current	50	mA

4869 tbl 05

NOTES:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{TERM} must not exceed V_{DD} + 150mV for more than 25% of the cycle time or 4ns maximum, and is limited to $\leq 20\text{mA}$ for the period of V_{TERM} $\geq$ V_{DD} + 150mV.

Capacitance⁽¹⁾

(TA = +25°C, F = 1.0MHz) PQFP ONLY

Symbol	Parameter	Conditions ⁽²⁾	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 3dV	8	pF
C _{OUT} ⁽³⁾	Output Capacitance	V _{OUT} = 3dV	10.5	pF

4869 tbl 06

NOTES:

1. These parameters are determined by device characterization, but are not production tested.
2. 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
3. C_{OUT} also references C_{IO}.

Recommended DC Operating Conditions with V_{DDQ} at 2.5V

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{DD}	Core Supply Voltage	3.15	3.3	3.45	V
V _{DDQ}	I/O Supply Voltage ⁽⁶⁾	2.4	2.5	2.6	V
V _{SS}	Ground	0	0	0	V
V _{IH}	Input High Voltage ⁽³⁾ (Address & Control Inputs)	1.7	—	V _{DDQ} + 100mV ⁽²⁾	V
V _{IH}	Input High Voltage - I/O ⁽³⁾	1.7	—	V _{DDQ} + 100mV ⁽²⁾	V
V _{IL}	Input Low Voltage	-0.5 ⁽¹⁾	—	0.7	V

4869 tbl 06

NOTES:

1. V_{IL} $\geq$ -1.5V for pulse width less than 10 ns.
2. V_{TERM} must not exceed V_{DDQ} + 100mV.
3. To select operation at 2.5V levels on the I/Os and controls of a given port, the OPT pin for that port must be set to V_{IL} (0V), and V_{DDQX} for that port must be supplied as indicated above.

Recommended DC Operating Conditions with V_{DDQ} at 3.3V

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{DD}	Core Supply Voltage	3.15	3.3	3.45	V
V _{DDQ}	I/O Supply Voltage ⁽⁶⁾	3.15	3.3	3.45	V
V _{SS}	Ground	0	0	0	V
V _{IH}	Input High Voltage (Address & Control Inputs) ⁽³⁾	2.0	—	V _{DDQ} + 150mV ⁽²⁾	V
V _{IH}	Input High Voltage - I/O ⁽³⁾	2.0	—	V _{DDQ} + 150mV ⁽²⁾	V
V _{IL}	Input Low Voltage	-0.3 ⁽¹⁾	—	0.8	V

4869 tbl 07

NOTES:

1. V_{IL} $\geq$ -1.5V for pulse width less than 10 ns.
2. V_{TERM} must not exceed V_{DDQ} + 150mV.
3. To select operation at 3.3V levels on the I/Os and controls of a given port, the OPT pin for that port must be set to V_{IH} (3.3V), and V_{DDQX} for that port must be supplied as indicated above.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ($V_{DD} = 3.3V \pm 150mV$)

Symbol	Parameter	Test Conditions	70V659S		Unit
			Min.	Max.	
$ I_{LI} $	Input Leakage Current ⁽¹⁾	$V_{DDQ} = \text{Max.}, V_{IN} = 0V \text{ to } V_{DDQ}$	—	10	μA
$ I_{LO} $	Output Leakage Current	$\overline{CE}_0 = V_{IH} \text{ or } CE_1 = V_{IL}, V_{OUT} = 0V \text{ to } V_{DDQ}$	—	10	μA
$V_{OL} (3.3V)$	Output Low Voltage ⁽²⁾	$I_{OL} = +4mA, V_{DDQ} = \text{Min.}$	—	0.4	V
$V_{OH} (3.3V)$	Output High Voltage ⁽²⁾	$I_{OH} = -4mA, V_{DDQ} = \text{Min.}$	2.4	—	V
$V_{OL} (2.5V)$	Output Low Voltage ⁽²⁾	$I_{OL} = +2mA, V_{DDQ} = \text{Min.}$	—	0.4	V
$V_{OH} (2.5V)$	Output High Voltage ⁽²⁾	$I_{OH} = -2mA, V_{DDQ} = \text{Min.}$	2.0	—	V

NOTE:

- At $V_{DD} \leq -2.0V$ input leakages are undefined.
- V_{DDQ} is selectable (3.3V/2.5V) via OPT pins. Refer to p.5 for details.

4869 tbl 09

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽³⁾ ($V_{DD} = 3.3V \pm 150mV$)

Symbol	Parameter	Test Condition	Version	70V659S10 Com'l Only		70V659S12 Com'l & Ind		70V659S15 Com'l & Ind		Unit
				Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	
I_{DD}	Dynamic Operating Current (Both Ports Active)	$\overline{CE}_L \text{ and } \overline{CE}_R = V_{IL},$ Outputs Disabled $f = f_{MAX}^{(1)}$	COM'L S	340	500	315	465	300	440	mA
			IND S	—	—	365	515	350	490	
ISB1	Standby Current (Both Ports - TTL Level Inputs)	$\overline{CE}_L = \overline{CE}_R = V_{IH}$ $f = f_{MAX}^{(1)}$	COM'L S	115	165	90	125	75	100	mA
			IND S	—	—	115	150	100	125	
ISB2	Standby Current (One Port - TTL Level Inputs)	$\overline{CE}^*A = V_{IL} \text{ and } \overline{CE}^*B = V_{IH}^{(5)}$ Active Port Outputs Disabled, $f = f_{MAX}^{(1)}$	COM'L S	225	340	200	325	175	315	mA
			IND S	—	—	225	365	200	350	
ISB3	Full Standby Current (Both Ports - CMOS Level Inputs)	Both Ports $\overline{CE}_L$ and $\overline{CE}_R \geq V_{DD} - 0.2V, V_{IN} \geq V_{DD} - 0.2V$ or $V_{IN} \leq 0.2V, f = 0^{(2)}$	COM'L S	3	15	3	15	3	15	mA
			IND S	—	—	6	15	6	15	
ISB4	Full Standby Current (One Port - CMOS Level Inputs)	$\overline{CE}^*A \leq 0.2V \text{ and } \overline{CE}^*B \geq V_{DD} - 0.2V^{(6)}$ $V_{IN} \geq V_{DD} - 0.2V \text{ or } V_{IN} \leq 0.2V, \text{ Active Port, Outputs Disabled, } f = f_{MAX}^{(1)}$	COM'L S	220	335	195	320	170	310	mA
			IND S	—	—	220	360	195	345	

NOTES:

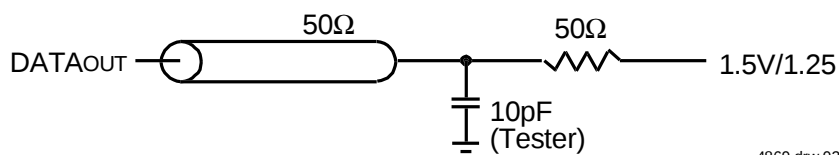
- At $f = f_{MAX}$, address and control lines (except Output Enable) are cycling at the maximum frequency read cycle of $1/t_{rc}$, using "AC TEST CONDITIONS" at input levels of GND to 3V.
- $f = 0$ means no address or control lines change. Applies only to input at CMOS level standby.
- Port "A" may be either left or right port. Port "B" is the opposite of port "A".
- $V_{DD} = 3.3V, T_A = 25^\circ C$ for Typ, and are not production tested. $I_{DD} \text{ dc}(f=0) = 120mA$ (Typ).
- $\overline{CE}_X = V_{IL}$ means $\overline{CE}_{0X} = V_{IL}$ and $CE_{1X} = V_{IH}$
 $\overline{CE}_X = V_{IH}$ means $\overline{CE}_{0X} = V_{IH}$ or $CE_{1X} = V_{IL}$
 $\overline{CE}_X \leq 0.2V$ means $\overline{CE}_{0X} \leq 0.2V$ and $CE_{1X} \geq V_{CC} - 0.2V$
 $\overline{CE}_X \geq V_{CC} - 0.2V$ means $\overline{CE}_{0X} \geq V_{CC} - 0.2V$ or $CE_{1X} \leq 0.2V$
 "X" represents "L" for left port or "R" for right port.

4869 tbl 10

AC Test Conditions ($V_{DDQ} = 3.3V/2.5V$)

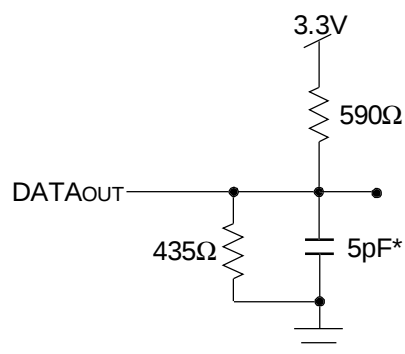
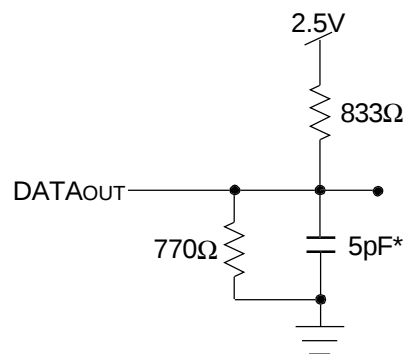
Input Pulse Levels	GND to 3.0V / GND to 2.5V
Input Rise/Fall Times	2ns Max.
Input Timing Reference Levels	1.5V/1.25V
Output Reference Levels	1.5V/1.25V
Output Load	Figures 1 and 2

4869 tbl 11



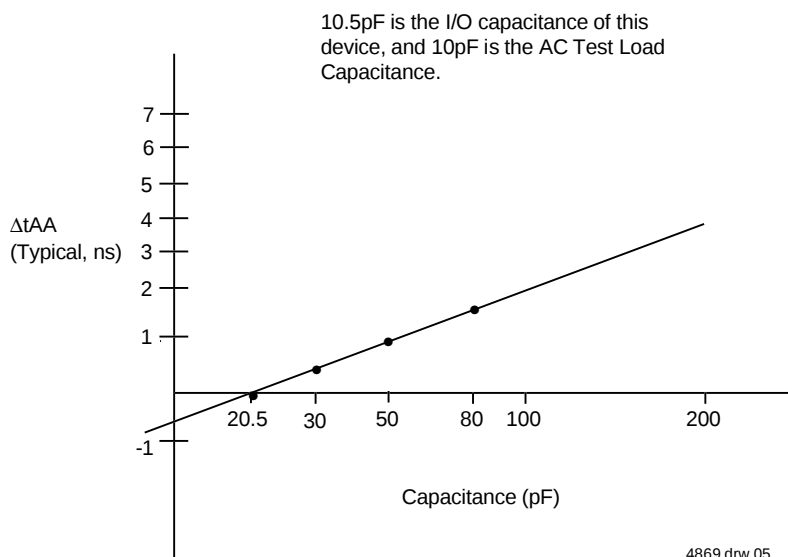
4869 drw 03

Figure 1. AC Output Test load.



4869 drw 04

Figure 2. Output Test Load
(For t_{CKLZ} , t_{CKHZ} , t_{OLZ} , and t_{OHZ}).
*Including scope and jig.



4869 drw 05

Figure 3. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁵⁾

Symbol	Parameter	70V659S10 Com'l Only		70V659S12 Com'l & Ind		70V659S15 Com'l & Ind		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
READ CYCLE								
t _{RC}	Read Cycle Time	10	—	12	—	15	—	ns
t _{AA}	Address Access Time	—	10	—	12	—	15	ns
t _{ACE}	Chip Enable Access Time ⁽³⁾	—	10	—	12	—	15	ns
t _{ABE}	Byte Enable Access Time ⁽³⁾	—	5	—	6	—	7	ns
t _{AOE}	Output Enable Access Time	—	5	—	6	—	7	ns
t _{OH}	Output Hold from Address Change	3	—	3	—	3	—	ns
t _{LZ}	Output Low-Z Time ^(1,2)	0	—	0	—	0	—	ns
t _{HZ}	Output High-Z Time ^(1,2)	0	4	0	6	0	8	ns
t _{PU}	Chip Enable to Power Up Time ⁽²⁾	0	—	0	—	0	—	ns
t _{PD}	Chip Disable to Power Down Time ⁽²⁾	—	10	—	10	—	15	ns
t _{SOP}	Semaphore Flag Update Pulse ($\overline{OE}$ or $\overline{SEM}$)	—	4	—	6	—	8	ns
t _{SAA}	Semaphore Address Access Time	3	10	3	12	3	20	ns

4869 tbl 12

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽⁵⁾

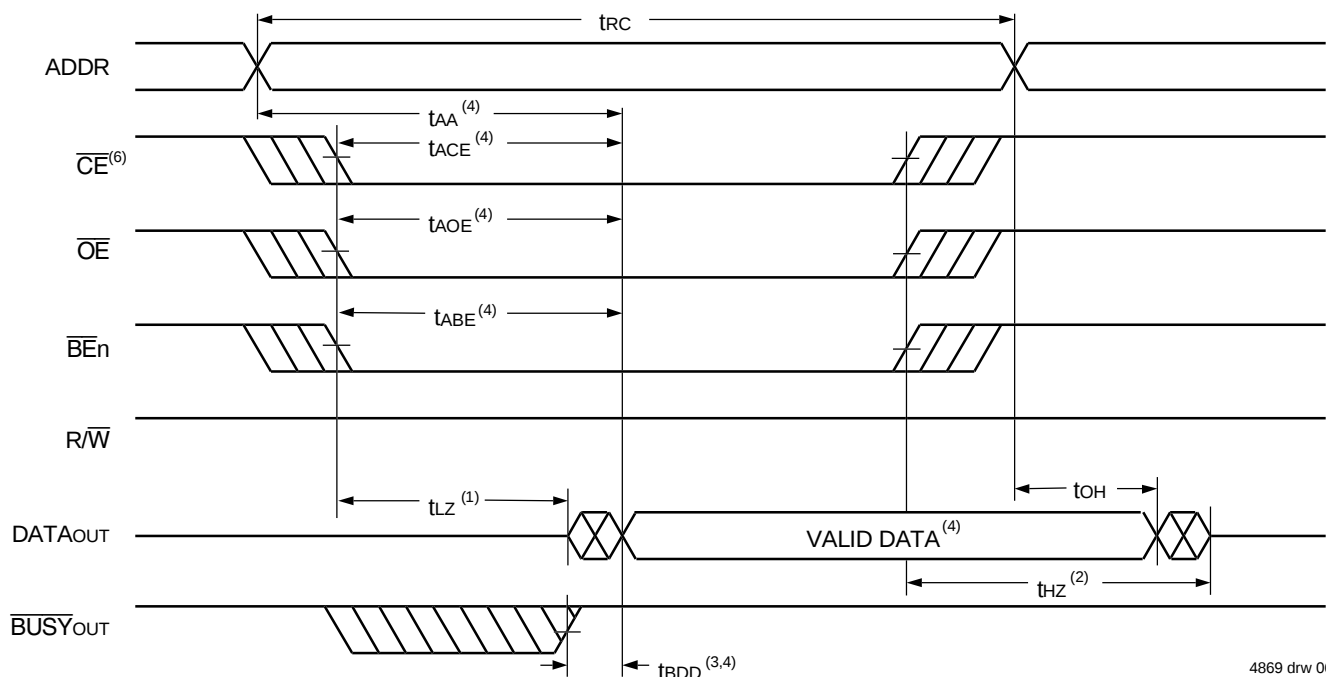
Symbol	Parameter	70V659S10 Com'l Only		70V659S12 Com'l & Ind		70V659S15 Com'l & Ind		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
WRITE CYCLE								
tWC	Write Cycle Time	10	—	12	—	15	—	ns
tEW	Chip Enable to End-of-Write ⁽³⁾	8	—	10	—	12	—	ns
tAW	Address Valid to End-of-Write	8	—	10	—	12	—	ns
tAS	Address Set-up Time ⁽³⁾	0	—	0	—	0	—	ns
tWP	Write Pulse Width	8	—	10	—	12	—	ns
tWR	Write Recovery Time	0	—	0	—	0	—	ns
tDW	Data Valid to End-of-Write	6	—	8	—	10	—	ns
tDH	Data Hold Time ⁽⁴⁾	0	—	0	—	0	—	ns
tWZ	Write Enable to Output in High-Z ^(1,2)	—	4	—	4	—	4	ns
tOW	Output Active from End-of-Write ^(1,2,4)	0	—	0	—	0	—	ns
tSWRD	$\overline{SEM}$ Flag Write to Read Time	5	—	5	—	5	—	ns
tSPS	$\overline{SEM}$ Flag Contention Window	5	—	5	—	5	—	ns

4869 tbl 13

NOTES:

1. Transition is measured 0mV from Low or High-impedance voltage with Output Test Load (Figure 2).
2. This parameter is guaranteed by device characterization, but is not production tested.
3. To access RAM, $\overline{CE} = V_{IL}$ and $\overline{SEM} = V_{IH}$. To access semaphore, $\overline{CE} = V_{IH}$ and $\overline{SEM} = V_{IL}$. Either condition must be valid for the entire t_{EW} time.
4. The specification for t_{DH} must be met by the device supplying write data to the RAM under all operating conditions. Although t_{DH} and t_{OW} values will vary over voltage and temperature, the actual t_{DH} will always be smaller than the actual t_{OW}.
5. These values are valid regardless of the power supply level selected for I/O and control signals (3.3V/2.5V). See page 5 for details.

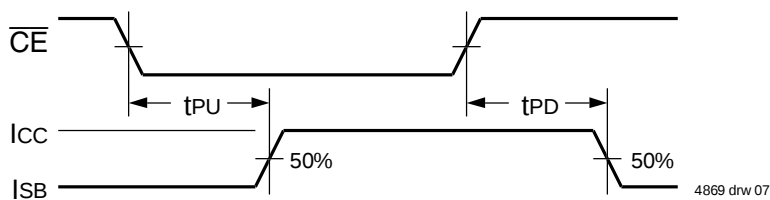
Waveform of Read Cycles⁽⁵⁾



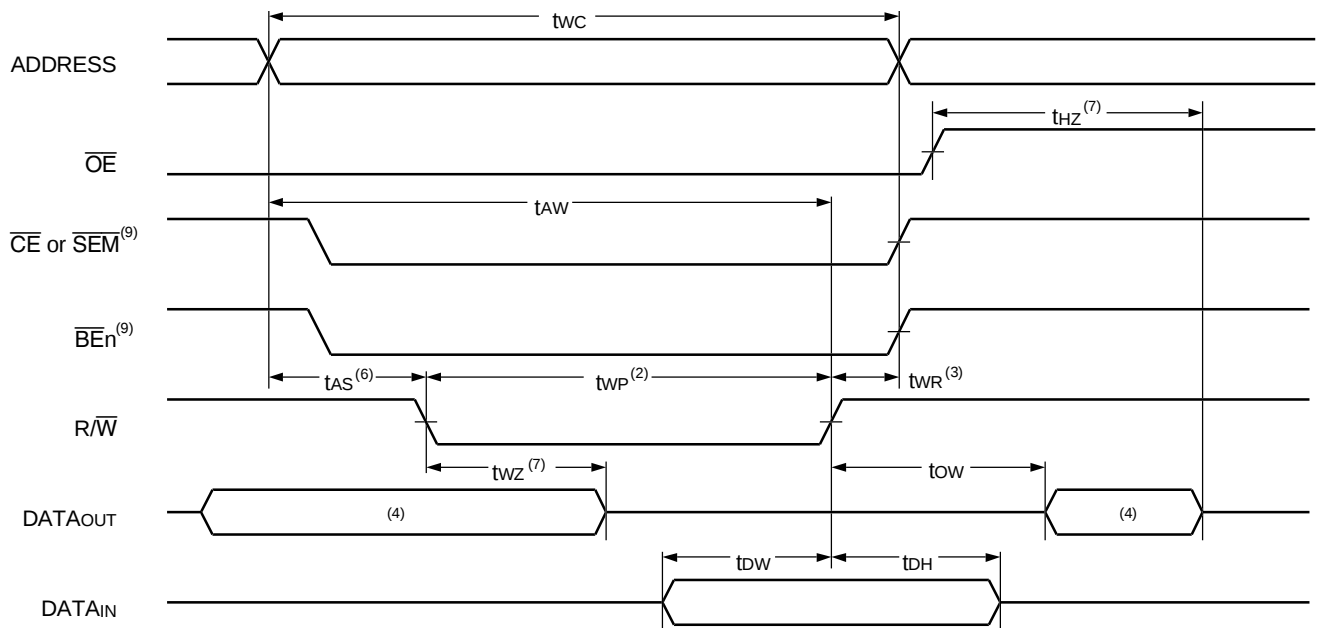
NOTES:

1. Timing depends on which signal is asserted last, $\overline{OE}$, $\overline{CE}$ or $\overline{BEn}$.
2. Timing depends on which signal is de-asserted first $\overline{CE}$, $\overline{OE}$ or $\overline{BEn}$.
3. t_{BDD} delay is required only in cases where the opposite port is completing a write operation to the same address location. For simultaneous read operations $\overline{BUSY}$ has no relation to valid output data.
4. Start of valid data depends on which timing becomes effective last t_{AOE} , t_{ACE} , t_{AA} or t_{BDD} .
5. $\overline{SEM} = V_{IH}$.

Timing of Power-Up Power-Down

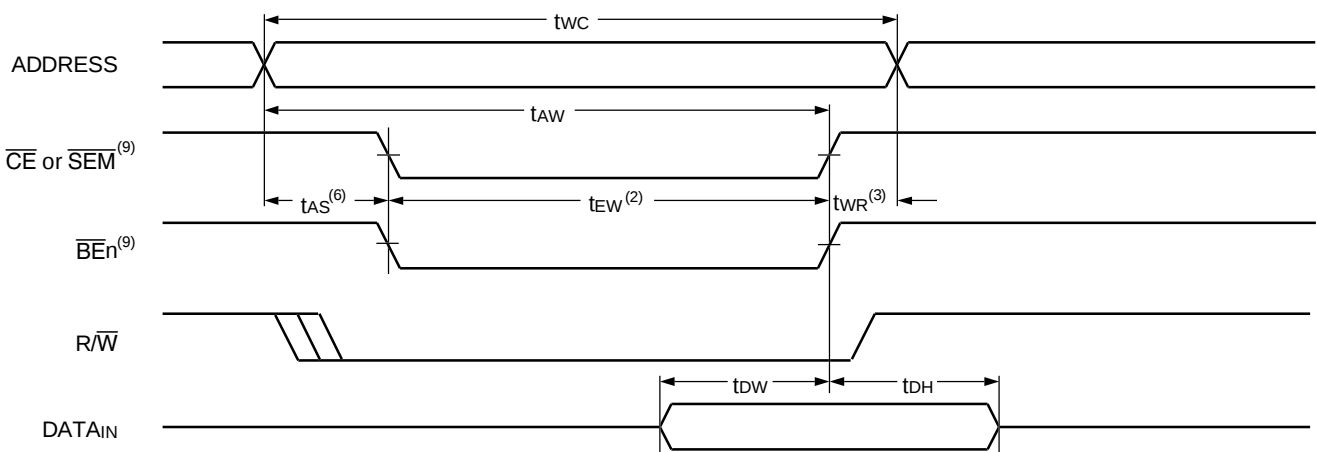


Timing Waveform of Write Cycle No. 1, R/W Controlled Timing^(1,5,8)



4869 drw 08

Timing Waveform of Write Cycle No. 2, CE Controlled Timing^(1,5)



4869 drw 09

NOTES:

1. $\overline{R/W}$ or $\overline{CE}$ or $\overline{BE_n}$ = V_{IH} during all address transitions.
2. A write occurs during the overlap (t_{EW} or t_{WP}) of a $\overline{CE} = V_{IL}$ and a $\overline{R/W} = V_{IL}$ for memory array writing cycle.
3. t_{WR} is measured from the earlier of $\overline{CE}$ or $\overline{R/W}$ (or $\overline{SEM}$ or $\overline{R/W}$) going HIGH to the end of write cycle.
4. During this period, the I/O pins are in the output state and input signals must not be applied.
5. If the $\overline{CE}$ or $\overline{SEM} = V_{IL}$ transition occurs simultaneously with or after the $\overline{R/W} = V_{IL}$ transition, the outputs remain in the High-impedance state.
6. Timing depends on which enable signal is asserted last, $\overline{CE}$ or $\overline{R/W}$.
7. This parameter is guaranteed by device characterization, but is not production tested. Transition is measured 0mV from steady state with the Output Test Load (Figure 2).
8. If $\overline{OE} = V_{IL}$ during $\overline{R/W}$ controlled write cycle, the write pulse width must be the larger of t_{WP} or ($t_{WZ} + t_{DW}$) to allow the I/O drivers to turn off and data to be placed on the bus for the required t_{DW} . If $\overline{OE} = V_{IH}$ during an $\overline{R/W}$ controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified t_{WP} .
9. To access RAM, $\overline{CE} = V_{IL}$ and $\overline{SEM} = V_{IH}$. To access semaphore, $\overline{CE} = V_{IH}$ and $\overline{SEM} = V_{IL}$. t_{EW} must be met for either condition.

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range

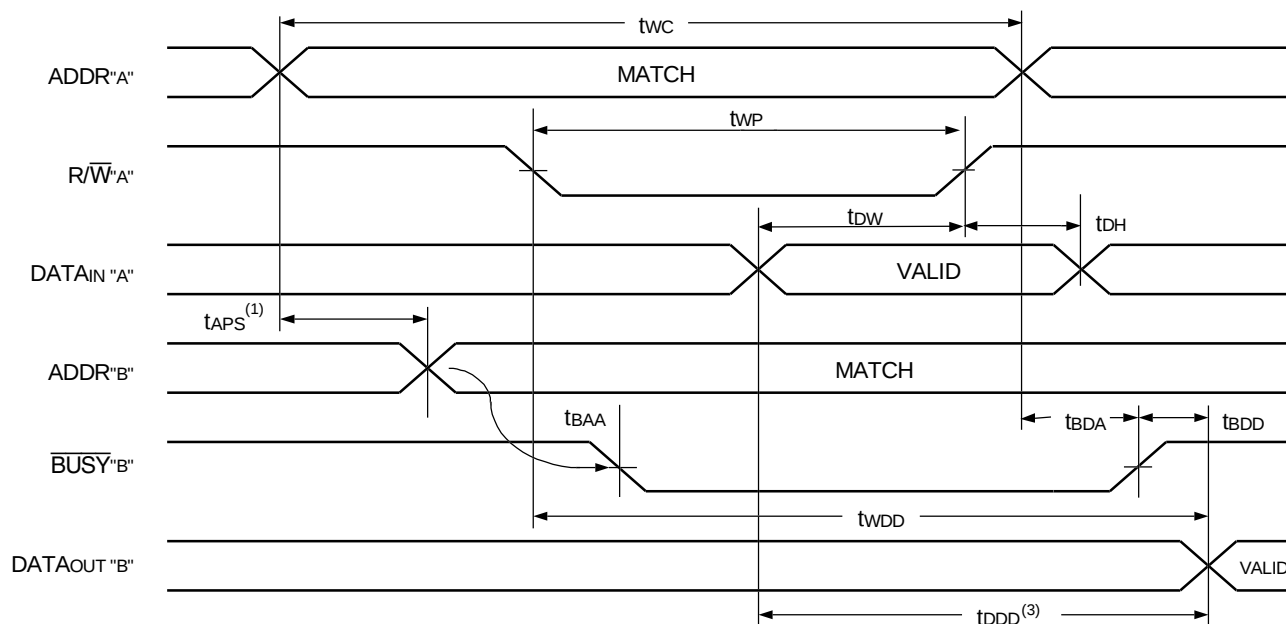
Symbol	Parameter	70V659S10 Com'l Only		70V659S12 Com'l & Ind		70V659S15 Com'l & Ind		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
BUSY TIMING (M/ $\overline{S}$ =V _{IH})								
t _{BAA}	$\overline{\text{BUSY}}$ Access Time from Address Match	—	10	—	12	—	15	ns
t _{BDA}	$\overline{\text{BUSY}}$ Disable Time from Address Not Matched	—	10	—	12	—	15	ns
t _{BAC}	$\overline{\text{BUSY}}$ Access Time from Chip Enable Low	—	10	—	12	—	15	ns
t _{BDC}	$\overline{\text{BUSY}}$ Disable Time from Chip Enable High	—	10	—	12	—	15	ns
t _{APS}	Arbitration Priority Set-up Time ⁽²⁾	5	—	5	—	5	—	ns
t _{BDD}	$\overline{\text{BUSY}}$ Disable to Valid Data ⁽³⁾	—	10	—	12	—	15	ns
t _{WH}	Write Hold After $\overline{\text{BUSY}}$ ⁽⁵⁾	8	—	10	—	12	—	ns
BUSY TIMING (M/ $\overline{S}$ =V _{IL})								
t _{WB}	$\overline{\text{BUSY}}$ Input to Write ⁽⁴⁾	0	—	0	—	0	—	ns
t _{WH}	Write Hold After $\overline{\text{BUSY}}$ ⁽⁵⁾	8	—	10	—	12	—	ns
PORT-TO-PORT DELAY TIMING								
t _{WDD}	Write Pulse to Data Delay ⁽¹⁾	—	22	—	25	—	30	ns
t _{DDD}	Write Data Valid to Read Data Delay ⁽¹⁾	—	20	—	22	—	25	ns

4869 tbl 14

NOTES:

- Port-to-port delay through RAM cells from writing port to reading port, refer to "Timing Waveform of Write with Port-to-Port Read and $\overline{\text{BUSY}}$ (M/ $\bar{S}$ = V_{IH})".
- To ensure that the earlier of the two ports wins.
- t_{BDD} is a calculated parameter and is the greater of the Max. spec, t_{WDD} – t_{WP} (actual), or t_{DDD} – t_{WD} (actual).
- To ensure that the write cycle is inhibited on port "B" during contention on port "A".
- To ensure that a write cycle is completed on port "B" after contention on port "A".

Timing Waveform of Write with Port-to-Port Read and $\overline{\text{BUSY}}$ ($\text{M}/\overline{\text{S}} = \text{V}_{\text{IH}}$)^(2,4,5)

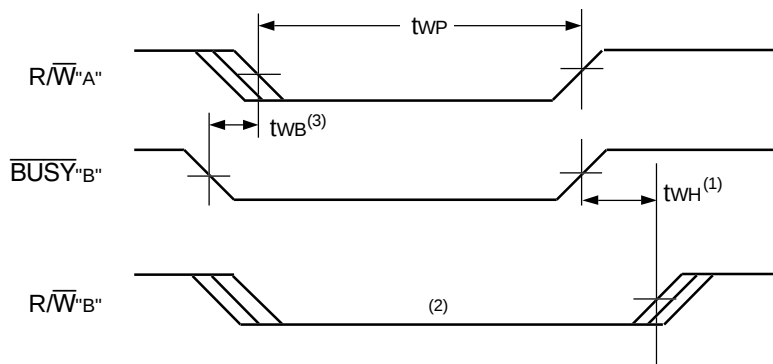


4869 drw 12

NOTES:

1. To ensure that the earlier of the two ports wins. t_{APS} is ignored for $\text{M}/\overline{\text{S}} = \text{V}_{\text{IL}}$ (SLAVE).
2. $\overline{\text{CEL}} = \overline{\text{CER}} = \text{V}_{\text{IL}}$.
3. $\overline{\text{OE}} = \text{V}_{\text{IL}}$ for the reading port.
4. If $\text{M}/\overline{\text{S}} = \text{V}_{\text{IL}}$ (slave), $\overline{\text{BUSY}}$ is an input. Then for this example $\overline{\text{BUSY}}^{\text{A}} = \text{V}_{\text{IH}}$ and $\overline{\text{BUSY}}^{\text{B}}$ input is shown above.
5. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".

Timing Waveform of Write with $\overline{\text{BUSY}}$ ($\text{M}/\overline{\text{S}} = \text{V}_{\text{IL}}$)

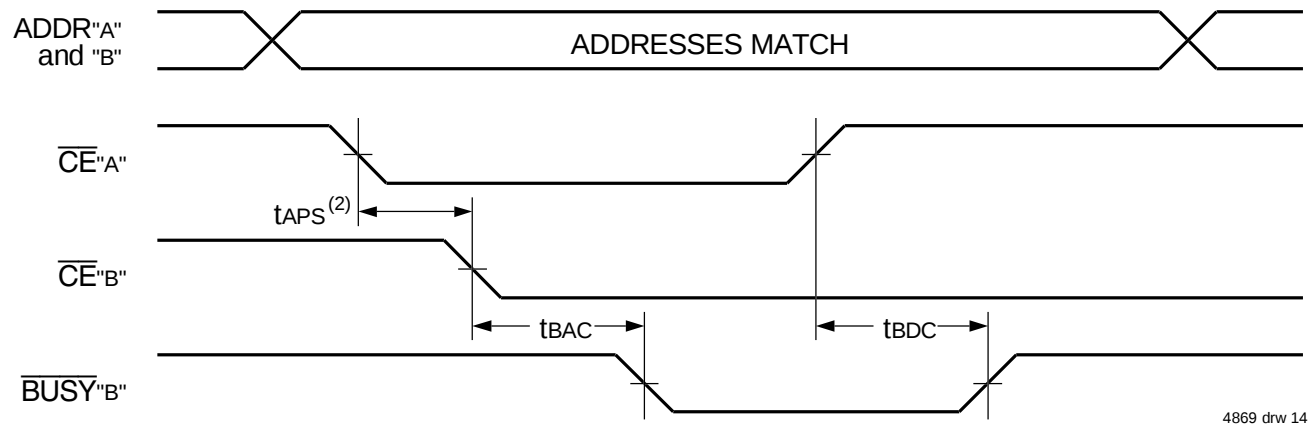


4869 drw 13

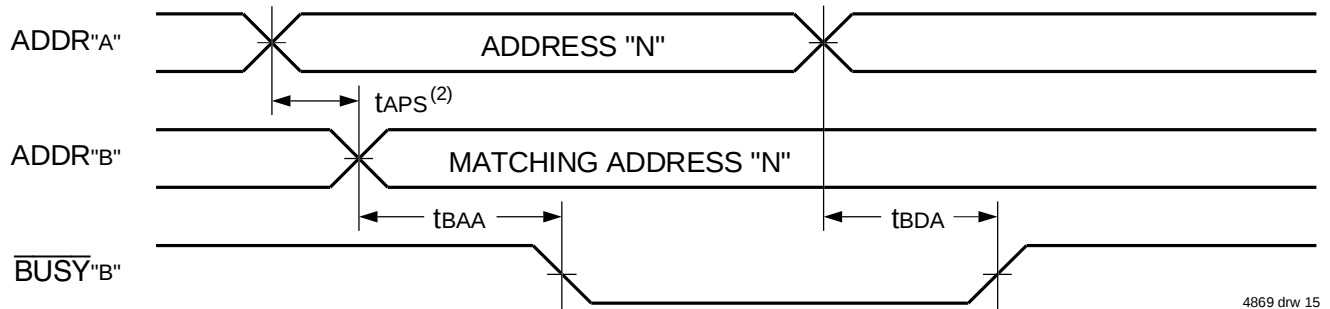
NOTES:

1. t_{WH} must be met for both $\overline{\text{BUSY}}$ input (SLAVE) and output (MASTER).
2. $\overline{\text{BUSY}}$ is asserted on port "B" blocking $\text{R}/\overline{\text{W}}^{\text{B}}$, until $\overline{\text{BUSY}}^{\text{B}}$ goes HIGH.
3. t_{WB} is only for the 'slave' version.

Waveform of $\overline{\text{BUSY}}$ Arbitration Controlled by $\overline{\text{CE}}$ Timing ($\text{M}/\overline{\text{S}} = \text{V}_{\text{IH}}$)⁽¹⁾



Waveform of $\overline{\text{BUSY}}$ Arbitration Cycle Controlled by Address Match Timing ($\text{M}/\overline{\text{S}} = \text{V}_{\text{IH}}$)⁽¹⁾



NOTES:

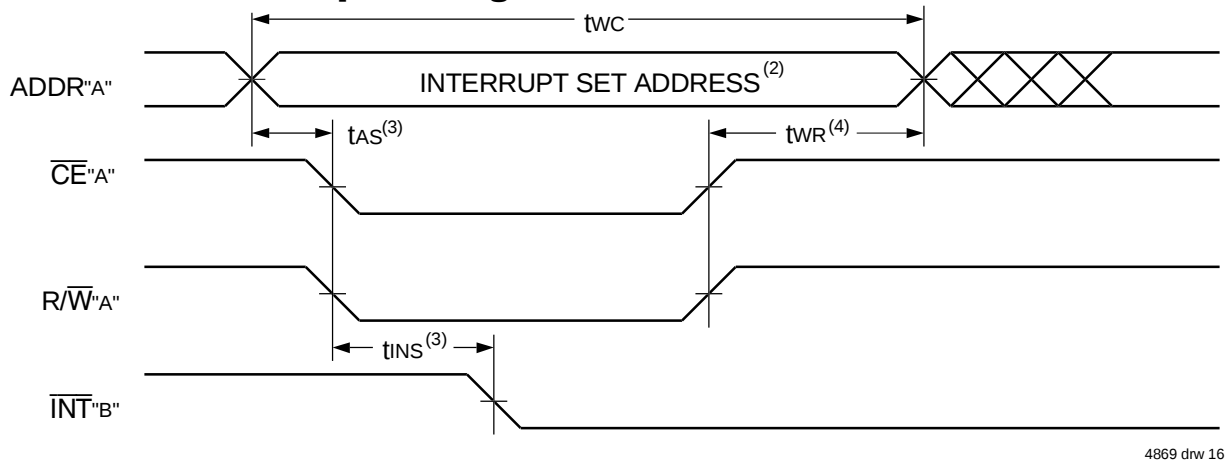
1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".
2. If t_{APS} is not satisfied, the $\overline{\text{BUSY}}$ signal will be asserted on one side or another but there is no guarantee on which side $\overline{\text{BUSY}}$ will be asserted.

AC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range

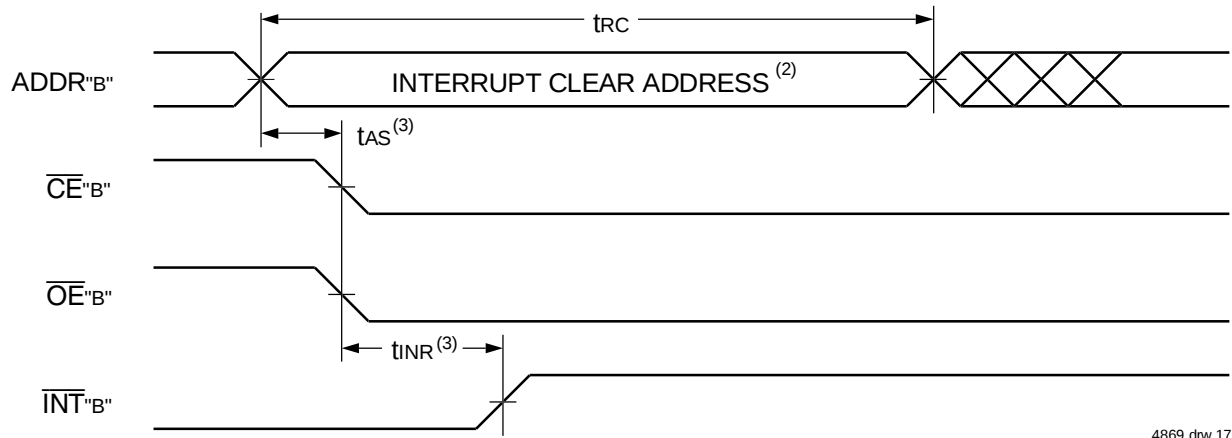
		70V659S10 Com'l Only		70V659S12 Com'l & Ind		70V659S15 Com'l & Ind		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
INTERRUPT TIMING								
tAS	Address Set-up Time	0	—	0	—	0	—	ns
tWR	Write Recovery Time	0	—	0	—	0	—	ns
tNS	Interrupt Set Time	—	10	—	12	—	15	ns
tNR	Interrupt Reset Time	—	10	—	12	—	15	ns

4869 tbl 15

Waveform of Interrupt Timing⁽¹⁾



4869 drw 16



4869 drw 17

NOTES:

1. All timing is the same for left and right ports. Port "A" may be either the left or right port. Port "B" is the port opposite from port "A".
2. Refer to Interrupt Truth Table.
3. Timing depends on which enable signal ($\overline{CE}$ or $R/\overline{W}$) is asserted last.
4. Timing depends on which enable signal ($\overline{CE}$ or $R/\overline{W}$) is de-asserted first.

Truth Table III — Interrupt Flag^(1,4)

Left Port					Right Port					Function
$R/\overline{W}_L$	$\overline{CE}_L$	$\overline{OE}_L$	A _{16L} -A _{0L}	$\overline{INT}_L$	$R/\overline{W}_R$	$\overline{CE}_R$	$\overline{OE}_R$	A _{16R} -A _{0R}	$\overline{INT}_R$	
L	L	X	1FFFF	X	X	X	X	X	L ⁽²⁾	Set Right $\overline{INT}_R$ Flag
X	X	X	X	X	X	L	L	1FFFF	H ⁽³⁾	Reset Right $\overline{INT}_R$ Flag
X	X	X	X	L ⁽³⁾	L	L	X	1FFFE	X	Set Left $\overline{INT}_L$ Flag
X	L	L	1FFFE	H ⁽²⁾	X	X	X	X	X	Reset Left $\overline{INT}_L$ Flag

NOTES:

1. Assumes $\overline{BUSY}_L = \overline{BUSY}_R = V_{IH}$.
2. If $\overline{BUSY}_L = V_{IL}$, then no change.
3. If $\overline{BUSY}_R = V_{IL}$, then no change.
4. $\overline{INT}_L$ and $\overline{INT}_R$ must be initialized at power-up.

4869 tbl 16

**Truth Table IV —
Address $\overline{BUSY}$ Arbitration**

Inputs			Outputs		Function
$\overline{CE_L}$	$\overline{CE_R}$	A0L-A16L A0R-A16R	$\overline{BUSY_L}^{(1)}$	$\overline{BUSY_R}^{(1)}$	
X	X	NO MATCH	H	H	Normal
H	X	MATCH	H	H	Normal
X	H	MATCH	H	H	Normal
L	L	MATCH	(2)	(2)	Write Inhibit ⁽³⁾

4869 tbl 17

NOTES:

1. Pins $\overline{BUSY_L}$ and $\overline{BUSY_R}$ are both outputs when the part is configured as a master. Both are inputs when configured as a slave. $\overline{BUSY}$ outputs on the IDT70V659 are push-pull, not open drain outputs. On slaves the $\overline{BUSY}$ input internally inhibits writes.
2. "L" if the inputs to the opposite port were stable prior to the address and enable inputs of this port. "H" if the inputs to the opposite port became stable after the address and enable inputs of this port. If t_{APS} is not met, either $\overline{BUSY_L}$ or $\overline{BUSY_R}$ = LOW will result. $\overline{BUSY_L}$ and $\overline{BUSY_R}$ outputs can not be LOW simultaneously.
3. Writes to the left port are internally ignored when $\overline{BUSY_L}$ outputs are driving LOW regardless of actual logic level on the pin. Writes to the right port are internally ignored when $\overline{BUSY_R}$ outputs are driving LOW regardless of actual logic level on the pin.

Truth Table V — Example of Semaphore Procurement Sequence^(1,2,3)

Functions	D0 - D35 Left	D0 - D35 Right	Status
No Action	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Right Port Writes "0" to Semaphore	0	1	No change. Right side has no write access to semaphore
Left Port Writes "1" to Semaphore	1	0	Right port obtains semaphore token
Left Port Writes "0" to Semaphore	1	0	No change. Left port has no write access to semaphore
Right Port Writes "1" to Semaphore	0	1	Left port obtains semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free
Right Port Writes "0" to Semaphore	1	0	Right port has semaphore token
Right Port Writes "1" to Semaphore	1	1	Semaphore free
Left Port Writes "0" to Semaphore	0	1	Left port has semaphore token
Left Port Writes "1" to Semaphore	1	1	Semaphore free

4869 tbl 18

NOTES:

1. This table denotes a sequence of events for only one of the eight semaphores on the IDT70V659.
2. There are eight semaphore flags written to via I/O₀ and read from all I/O's (I/O₀-I/O₃₅). These eight semaphores are addressed by A₀ - A₂.
3. $\overline{CE} = V_{IH}$, $\overline{SEM} = V_{IL}$ to access the semaphores. Refer to the Semaphore Read/Write Control Truth Table.

Functional Description

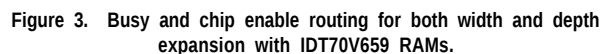
The IDT70V659 provides two ports with separate control, address and I/O pins that permit independent access for reads or writes to any location in memory. The IDT70V659 has an automatic power down feature controlled by $\overline{CE}$. The $\overline{CE_0}$ and $\overline{CE_1}$ control the on-chip power down circuitry that permits the respective port to go into a standby mode when not selected ($\overline{CE} = \text{HIGH}$). When a port is enabled, access to the entire memory array is permitted.

Interrupts

If the user chooses the interrupt function, a memory location (mail box or message center) is assigned to each port. The left port interrupt flag ($\overline{INT_L}$) is asserted when the right port writes to memory location

1FFFE (HEX), where a write is defined as $\overline{CE_R} = R/\overline{W_R} = V_{IL}$ per the Truth Table. The left port clears the interrupt through access of address location 1FFFE when $\overline{CE_L} = \overline{OE_L} = V_{IL}$, $R/\overline{W} = \text{"don't care"}$. Likewise, the right port interrupt flag ($\overline{INT_R}$) is asserted when the left port writes to memory location 1FFFF (HEX) and to clear the interrupt flag ($\overline{INT_R}$), the right port must read the memory location 1FFFF. The message (36 bits) at 1FFFE or 1FFFF is user-defined since it is an addressable SRAM location. If the interrupt function is not used, address locations 1FFFE and 1FFFF are not used as mail boxes, but as part of the random access memory. Refer to Truth Table III for the interrupt operation.

The BUSY outputs on the IDT70V659 RAM in master mode, are push-pull type outputs and do not require pull up resistors to operate. If these RAMs are being expanded in depth, then the BUSY indication for the resulting array requires the use of an external AND gate.



The **BUSY** arbitration on a master is based on the chip enable and

The semaphore logic is a set of eight latches which are independent of the Dual-Port RAM. These latches can be used to pass a flag, or token, from one port to the other to indicate that a shared resource is in use. The semaphores provide a hardware assist for a use assignment method called "Token Passing Allocation." In this method, the state of a semaphore latch is used as a token indicating that a shared resource is in use. If the left processor wants to use this resource, it requests the token by setting the latch. This processor then

verifies its success in setting the latch by reading it. If it was successful, it proceeds to assume control over the shared resource. If it was not successful in setting the latch, it determines that the right side processor has set the latch first, has the token and is using the shared resource. The left processor can then either repeatedly request that semaphore's status or remove its request for that semaphore to perform another task and occasionally attempt again to gain control of the token via the set and test sequence. Once the right side has relinquished the token, the left side should succeed in gaining control.

The semaphore flags are active LOW. A token is requested by writing a zero into a semaphore latch and is released when the same side writes a one to that latch.

The eight semaphore flags reside within the IDT70V659 in a separate memory space from the Dual-Port RAM. This address space is accessed by placing a low input on the $\overline{\text{SEM}}$ pin (which acts as a chip select for the semaphore flags) and using the other control pins (Address, $\overline{\text{CE}}$, $\text{R}/\overline{\text{W}}$ and $\overline{\text{BE}}$) as they would be used in accessing a standard Static RAM. Each of the flags has a unique address which can be accessed by either side through address pins A0 – A2. When accessing the semaphores, none of the other address pins has any effect.

When writing to a semaphore, only data pin D0 is used. If a low level is written into an unused semaphore location, that flag will be set to a zero on that side and a one on the other side (see Truth Table V). That semaphore can now only be modified by the side showing the zero. When a one is written into the same location from the same side, the flag will be set to a one for both sides (unless a semaphore request from the other side is pending) and then can be written to by both sides. The fact that the side which is able to write a zero into a semaphore subsequently locks out writes from the other side is what makes semaphore flags useful in interprocessor communications. (A thorough discussion on the use of this feature follows shortly.) A zero written into the same location from the other side will be stored in the semaphore request latch for that side until the semaphore is freed by the first side.

When a semaphore flag is read, its value is spread into all data bits so that a flag that is a one reads as a one in all data bits and a flag containing a zero reads as all zeros. The read value is latched into one side's output register when that side's semaphore select ($\overline{\text{SEM}}$, $\overline{\text{BEN}}$) and output enable ($\overline{\text{OE}}$) signals go active. This serves to disallow the semaphore from changing state in the middle of a read cycle due to a write cycle from the other side. Because of this latch, a repeated read of a semaphore in a test loop must cause either signal ($\overline{\text{SEM}}$ or $\overline{\text{OE}}$) to go inactive or the output will never change. However, during reads $\overline{\text{BEN}}$ functions only as an output for semaphore. It does not have any influence on the semaphore control logic.

A sequence WRITE/READ must be used by the semaphore in order to guarantee that no system level contention will occur. A processor requests access to shared resources by attempting to write a zero into a semaphore location. If the semaphore is already in use, the semaphore request latch will contain a zero, yet the semaphore flag will appear as one, a fact which the processor will verify by the subsequent read (see Table V). As an example, assume a processor writes a zero to the left port at a free semaphore location. On a subsequent read, the processor will verify that it has written successfully to that location and will assume control over the resource in

question. Meanwhile, if a processor on the right side attempts to write a zero to the same semaphore flag it will fail, as will be verified by the fact that a one will be read from that semaphore on the right side during subsequent read. Had a sequence of READ/WRITE been used instead, system contention problems could have occurred during the gap between the read and write cycles.

It is important to note that a failed semaphore request must be followed by either repeated reads or by writing a one into the same location. The reason for this is easily understood by looking at the simple logic diagram of the semaphore flag in Figure 4. Two semaphore request latches feed into a semaphore flag. Whichever latch is first to present a zero to the semaphore flag will force its side of the semaphore flag LOW and the other side HIGH. This condition will

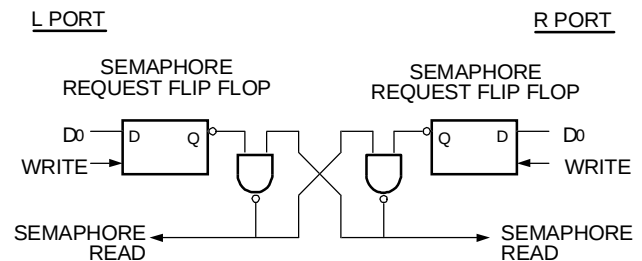


Figure 4. IDT70V659 Semaphore Logic

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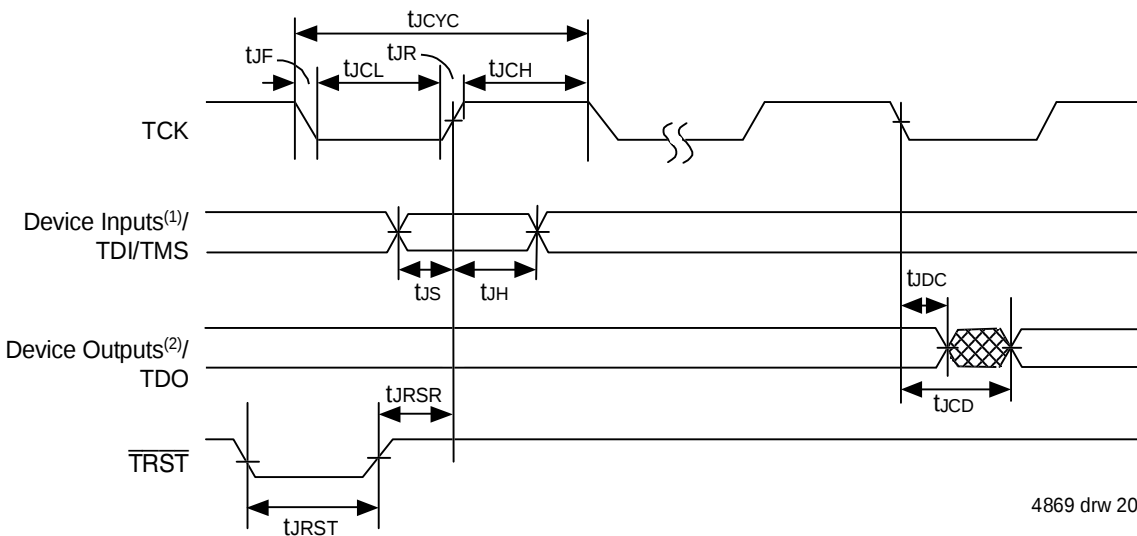
continue until a one is written to the same semaphore request latch. Should the other side's semaphore request latch have been written to a zero in the meantime, the semaphore flag will flip over to the other side as soon as a one is written into the first side's request latch. The second side's flag will now stay LOW until its semaphore request latch is written to a one. From this it is easy to understand that, if a semaphore is requested and the processor which requested it no longer needs the resource, the entire system can hang up until a one is written into that semaphore request latch.

The critical case of semaphore timing is when both sides request a single token by attempting to write a zero into it at the same time. The semaphore logic is specially designed to resolve this problem. If simultaneous requests are made, the logic guarantees that only one side receives the token. If one side is earlier than the other in making the request, the first side to make the request will receive the token. If both requests arrive at the same time, the assignment will be arbitrarily made to one port or the other.

One caution that should be noted when using semaphores is that semaphores alone do not guarantee that access to a resource is secure. As with any powerful programming technique, if semaphores are misused or misinterpreted, a software error can easily happen.

Initialization of the semaphores is not automatic and must be handled via the initialization program at power-up. Since any semaphore request flag which contains a zero must be reset to a one, all semaphores on both sides should have a one written into them at initialization from both sides to assure that they will be free when needed.

JTAG Timing Specifications



NOTES:

1. Device inputs = All device inputs except TDI, TMS, and TRST.
2. Device outputs = All device outputs except TDO.

JTAG AC Electrical Characteristics^(1,2,3,4)

Symbol	Parameter			
		Min.	Max.	Units
t_{JCYC}	JTAG Clock Input Period	100	—	ns
t_{JCH}	JTAG Clock HIGH	40	—	ns
t_{JCL}	JTAG Clock Low	40	—	ns
t_{JR}	JTAG Clock Rise Time	—	3 ⁽¹⁾	ns
t_{JF}	JTAG Clock Fall Time	—	3 ⁽¹⁾	ns
t_{JRST}	JTAG Reset	50	—	ns
t_{JRSR}	JTAG Reset Recovery	50	—	ns
t_{JCD}	JTAG Data Output	—	25	ns
t_{JDC}	JTAG Data Output Hold	0	—	ns
t_{JS}	JTAG Setup	15	—	ns
t_{JH}	JTAG Hold	15	—	ns

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NOTES:

1. Guaranteed by design.
2. 30pF loading on external output signals.
3. Refer to AC Electrical Test Conditions stated earlier in this document.
4. JTAG operations occur at one speed (10MHz). The base device may run at any speed specified in this datasheet.

Identification Register Definitions

Instruction Field	Value	Description
Revision Number (31:28)	0x0	Reserved for version number
IDT Device ID (27:12)	0x303	Defines IDT part number
IDT JEDEC ID (11:1)	0x33	Allows unique identification of device vendor as IDT
ID Register Indicator Bit (Bit 0)	1	Indicates the presence of an ID register

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Scan Register Sizes

Register Name	Bit Size
Instruction (IR)	4
Bypass (BYR)	1
Identification (IDR)	32
Boundary Scan (BSR)	Note (3)

4869 tbl 21

System Interface Parameters

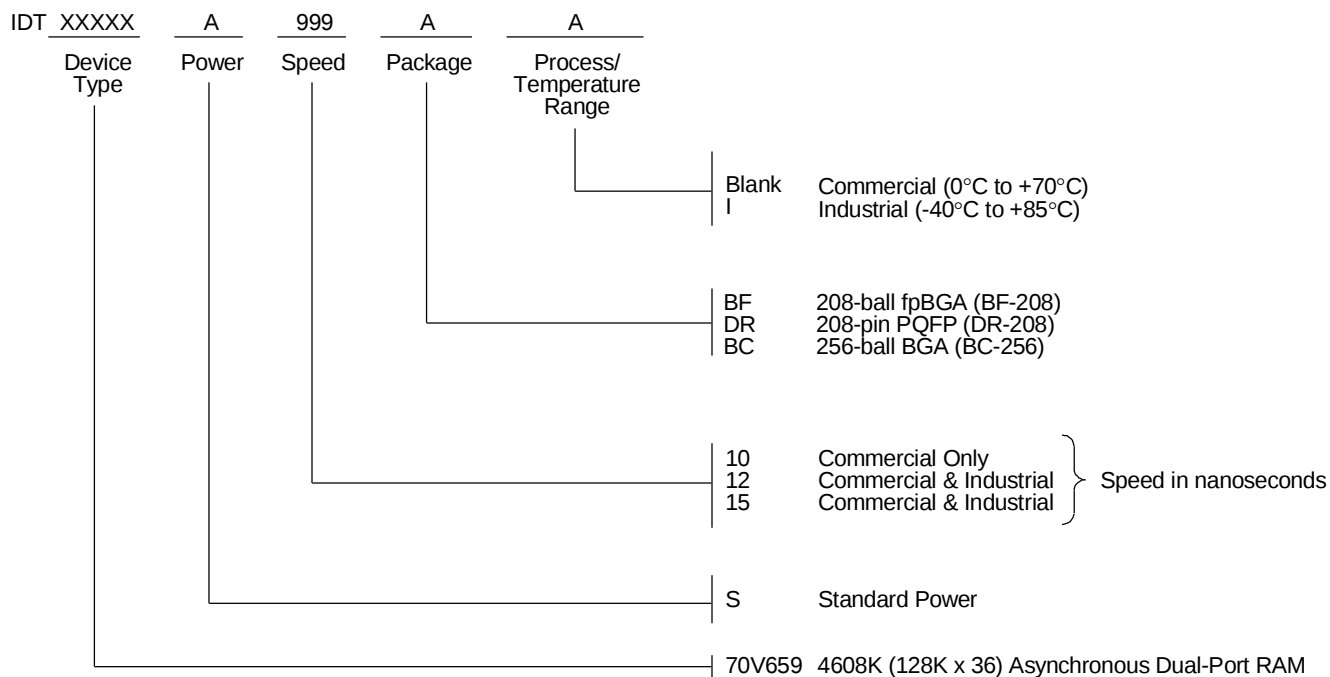
Instruction	Code	Description
EXTEST	0000	Forces contents of the boundary scan cells onto the device outputs ⁽¹⁾ . Places the boundary scan register (BSR) between TDI and TDO.
BYPASS	1111	Places the bypass register (BYR) between TDI and TDO.
IDCODE	0010	Loads the ID register (IDR) with the vendor ID code and places the register between TDI and TDO.
HIGHZ	0100	Places the bypass register (BYR) between TDI and TDO. Forces all device output drivers to a High-Z state.
CLAMP	0011	Uses BYR. Forces contents of the boundary scan cells onto the device outputs. Places the bypass register (BYR) between TDI and TDO.
SAMPLE/PRELOAD	0001	Places the boundary scan register (BSR) between TDI and TDO. SAMPLE allows data from device inputs ⁽²⁾ and outputs ⁽¹⁾ to be captured in the boundary scan cells and shifted serially through TDO. PRELOAD allows data to be input serially into the boundary scan cells via the TDI.
RESERVED	All other codes	Several combinations are reserved. Do not use codes other than those identified above.

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NOTES:

1. Device outputs = All device outputs except TDO.
2. Device inputs = All device inputs except TDI, TMS, and $\overline{\text{TRST}}$.
3. The Boundary Scan Descriptive Language (BSDL) file for this device is available on the IDT website (www.idt.com), or by contacting your local IDT sales representative.

Ordering Information



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Preliminary Datasheet: Definition

"PRELIMINARY" datasheets contain descriptions for products that are in early release.

Datasheet Document History:

- 6/2/00: Initial Public Offering.
- 8/11/00: Inserted additional $\overline{BEn}$ information on pages 6,13,20.
- 6/20/01: Increased $\overline{BUSY}$ TIMING parameters t_{BDA} , t_{BAC} , t_{BDC} and t_{BDD} for all speeds on page 14.
 Changed maximum value for JTAG AC Electrical Characteristics for t_{JCD} from 20ns to 25ns on page 21.



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